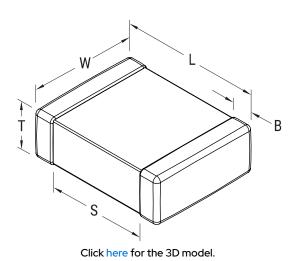




SMD Comm X8G HT150C Flex, Ceramic, 0.01 uF, 20%, 100 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	190 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		
Chip Size	2220	
L	5.9mm +/-0.75mm	
W	5mm +/-0.4mm	
Т	1.4mm +/-0.15mm	
S	3.5mm MIN	
В	0.7mm +/-0.35mm	

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S	3.5mm MIN
В	0.7mm +/-0.35mm
Packaging Specifications	

Specifications	
Capacitance	0.01 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Packaging	T&R, 330mm, Plastic Tape	Applied (TCC)
Packaging Quantity	4000	Dissipation Factor
		Aging Rate

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